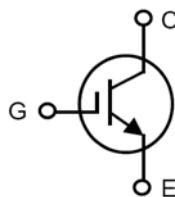


XPT™ 650V IGBT GenX3™

IXYH75N65C3

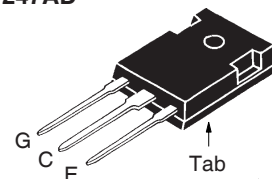


$V_{CES} = 650V$
 $I_{C110} = 75A$
 $V_{CE(sat)} \leq 2.3V$
 $t_{fi(typ)} = 60ns$

Extreme Light Punch through IGBT for 20-60kHz Switching

| Symbol | Test Conditions | Maximum Ratings | |
|-------------------------------|---|---|------------|
| V_{CES} | $T_J = 25^\circ C$ to $175^\circ C$ | 650 | V |
| V_{CGR} | $T_J = 25^\circ C$ to $175^\circ C$, $R_{GE} = 1M\Omega$ | 650 | V |
| V_{GES} | Continuous | ± 20 | V |
| V_{GEM} | Transient | ± 30 | V |
| I_{C25} | $T_C = 25^\circ C$ (Chip Capability) | 175 | A |
| I_{LRMS} | Terminal Current Limit | 160 | A |
| I_{C110} | $T_C = 110^\circ C$ | 75 | A |
| I_{CM} | $T_C = 25^\circ C$, 1ms | 360 | A |
| I_A | $T_C = 25^\circ C$ | 30 | A |
| E_{AS} | $T_C = 25^\circ C$ | 300 | mJ |
| SSOA (RBSOA) | $V_{GE} = 15V$, $T_{VJ} = 150^\circ C$, $R_G = 3\Omega$ Clamped Inductive Load | $I_{CM} = 150$ $V_{CE} \leq V_{CES}$ | A |
| t_{sc} (SCSOA) | $V_{GE} = 15V$, $V_{CE} = 360V$, $T_J = 150^\circ C$ $R_G = 82\Omega$, Non Repetitive | 8 | μs |
| P_C | $T_C = 25^\circ C$ | 750 | W |
| T_J | | -55 ... +175 | $^\circ C$ |
| T_{JM} | | 175 | $^\circ C$ |
| T_{stg} | | -55 ... +175 | $^\circ C$ |
| T_L | Maximum Lead Temperature for Soldering | 300 | $^\circ C$ |
| T_{SOLD} | 1.6 mm (0.062in.) from Case for 10s | 260 | $^\circ C$ |
| M_d | Mounting Torque | 1.13/10 | Nm/lb.in |
| Weight | | 6 | g |

TO-247AD



G = Gate C = Collector
 E = Emitter Tab = Collector

Features

- International Standard Package
- Optimized for 20-60kHz Switching
- Square RBSOA
- Avalanche Rated
- Short Circuit Capability
- High Current Handling Capability

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

| Symbol | Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified) | Characteristic Values | | |
|---------------|---|-----------------------|------------|---------------------------|
| | | Min. | Typ. | Max. |
| BV_{CES} | $I_C = 250\mu A$, $V_{GE} = 0V$ | 650 | | V |
| $V_{GE(th)}$ | $I_C = 250\mu A$, $V_{CE} = V_{GE}$ | 3.5 | | 6.0 V |
| I_{CES} | $V_{CE} = V_{CES}$, $V_{GE} = 0V$ $T_J = 150^\circ C$ | | | 10 μA 500 μA |
| I_{GES} | $V_{CE} = 0V$, $V_{GE} = \pm 20V$ | | | ± 100 nA |
| $V_{CE(sat)}$ | $I_C = 60A$, $V_{GE} = 15V$, Note 1 $T_J = 150^\circ C$ | | 1.8 2.2 | 2.3 V V |

Symbol Test Conditions

($T_J = 25^\circ\text{C}$ Unless Otherwise Specified)

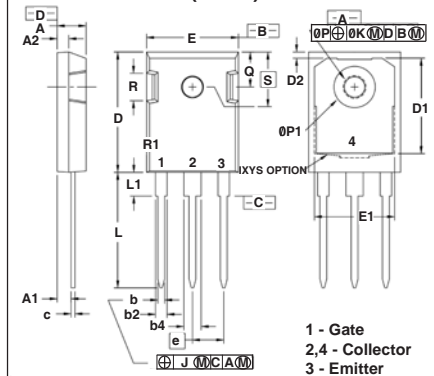
Characteristic Values

| | | Characteristic Values | | |
|--------------|---|-----------------------|------|---------------------------|
| | | Min. | Typ. | Max. |
| g_{fs} | $I_C = 60\text{A}, V_{CE} = 10\text{V}$, Note 1 | 25 | 44 | S |
| C_{ies} | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$ | | 3410 | pF |
| C_{oes} | | | 190 | pF |
| C_{res} | | | 73 | pF |
| $Q_{g(on)}$ | $I_C = 60\text{A}, V_{GE} = 15\text{V}, V_{CE} = 0.5 \cdot V_{CES}$ | | 122 | nC |
| Q_{ge} | | | 22 | nC |
| Q_{gc} | | | 60 | nC |
| $t_{d(on)}$ | Inductive load, $T_J = 25^\circ\text{C}$ $I_C = 60\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 3\Omega$ Note 2 | | 26 | ns |
| t_{ri} | | | 65 | ns |
| E_{on} | | | 2.00 | mJ |
| $t_{d(off)}$ | | | 93 | ns |
| t_{fi} | | | 60 | ns |
| E_{off} | | | 0.95 | mJ |
| $t_{d(on)}$ | Inductive load, $T_J = 150^\circ\text{C}$ $I_C = 60\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 3\Omega$ Note 2 | | 26 | ns |
| t_{ri} | | | 64 | ns |
| E_{on} | | | 3.40 | mJ |
| $t_{d(off)}$ | | | 115 | ns |
| t_{fi} | | | 64 | ns |
| E_{off} | | | 1.30 | mJ |
| R_{thJC} | | | 0.20 | $^\circ\text{C}/\text{W}$ |
| R_{thCS} | | 0.21 | | $^\circ\text{C}/\text{W}$ |

Notes:

1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.
2. Switching times & energy losses may increase for higher V_{CE} (clamp), T_J or R_G .

TO-247 (IXYH) Outline



| Dim. | Millimeter | | Inches | |
|------|------------|-------|-----------|-------|
| | min | max | min | max |
| A | 4.70 | 5.30 | 0.185 | 0.209 |
| A1 | 2.21 | 2.59 | 0.087 | 0.102 |
| A2 | 1.50 | 2.49 | 0.059 | 0.098 |
| b | 0.99 | 1.40 | 0.039 | 0.055 |
| b2 | 1.65 | 2.39 | 0.065 | 0.094 |
| b4 | 2.59 | 3.43 | 0.102 | 0.135 |
| c | 0.38 | 0.89 | 0.015 | 0.035 |
| D | 20.79 | 21.45 | 0.819 | 0.845 |
| D1 | 13.07 | - | 0.515 | - |
| D2 | 0.51 | 1.35 | 0.020 | 0.053 |
| E | 15.48 | 16.24 | 0.610 | 0.640 |
| E1 | 13.45 | - | 0.53 | - |
| E2 | 4.31 | 5.48 | 0.170 | 0.216 |
| e | 5.45 BSC | | 0.215 BSC | |
| L | 19.80 | 20.30 | 0.078 | 0.800 |
| L1 | - | 4.49 | - | 0.177 |
| Ø P | 3.55 | 3.65 | 0.140 | 0.144 |
| Ø P1 | - | 7.39 | - | 0.290 |
| Q | 5.38 | 6.19 | 0.212 | 0.244 |
| S | 6.14 BSC | | 0.242 BSC | |

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

| | | | | | | | | | | |
|--|-----------|-----------|-----------|-----------|--------------|--------------|--------------|--------------|--------------|-------------|
| IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
| | 4,860,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405 B2 | 6,759,692 | 7,063,975 B2 | |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

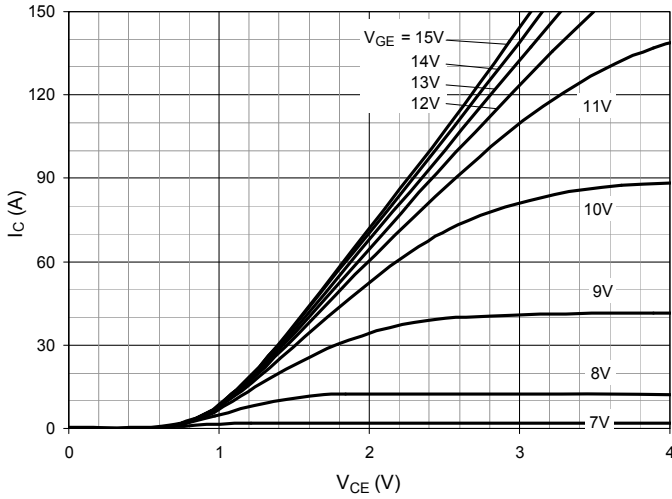
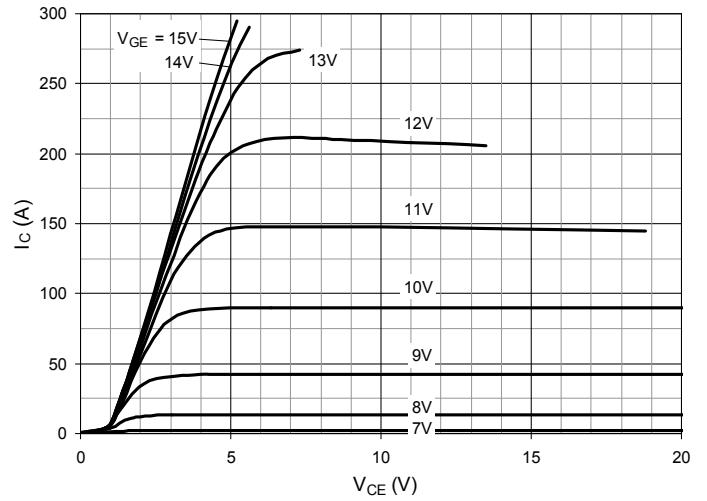
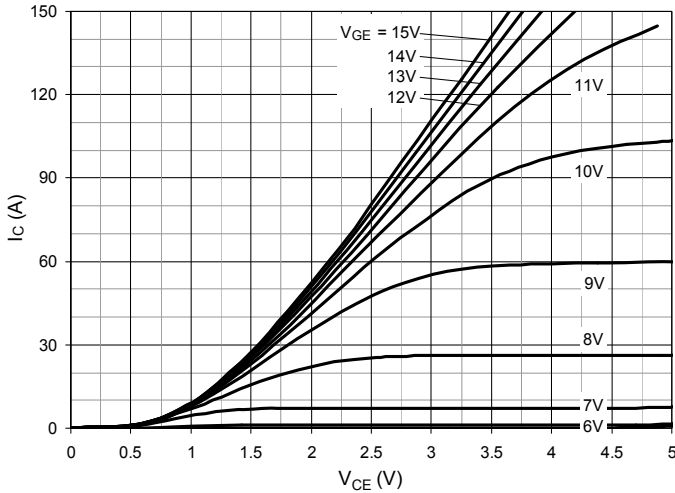
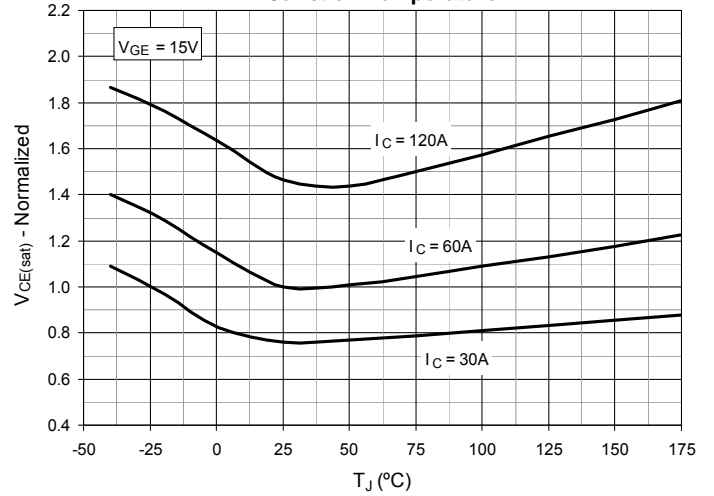
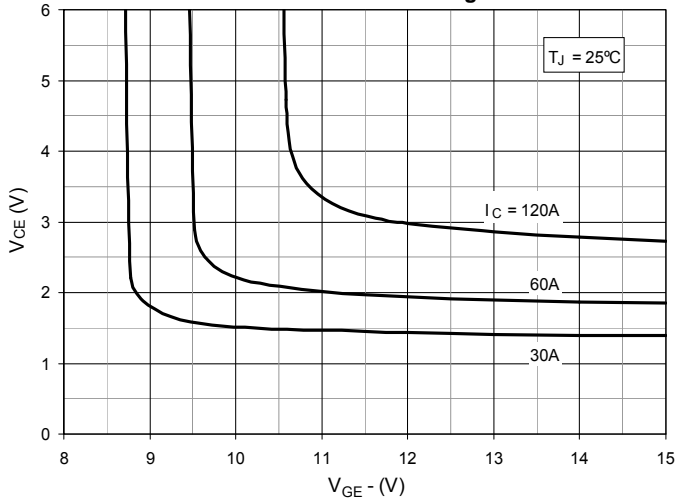
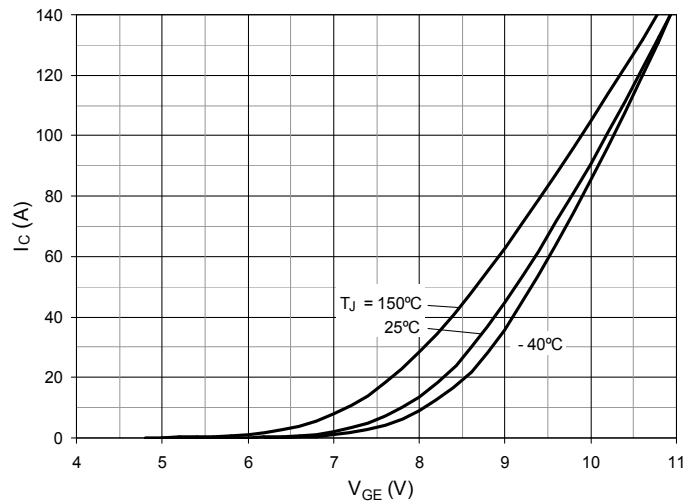
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$

Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

Fig. 6. Input Admittance


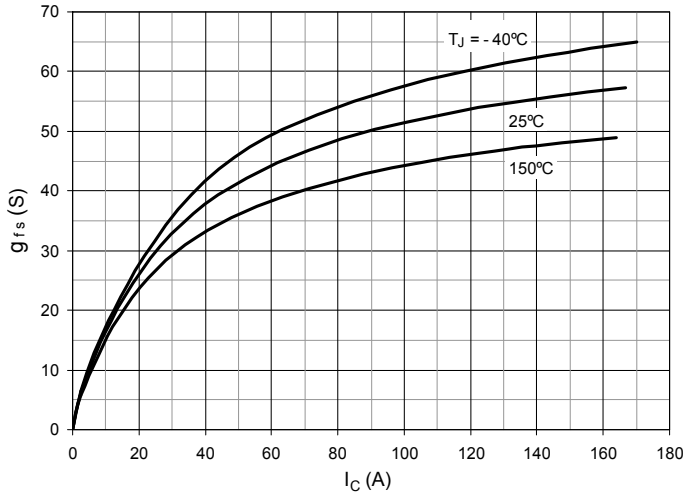
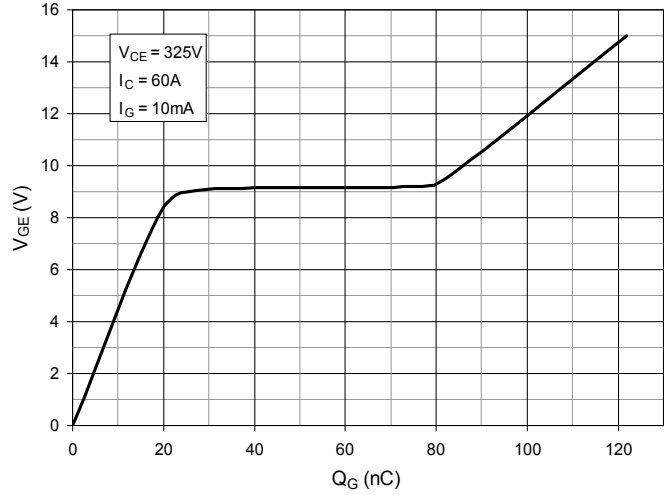
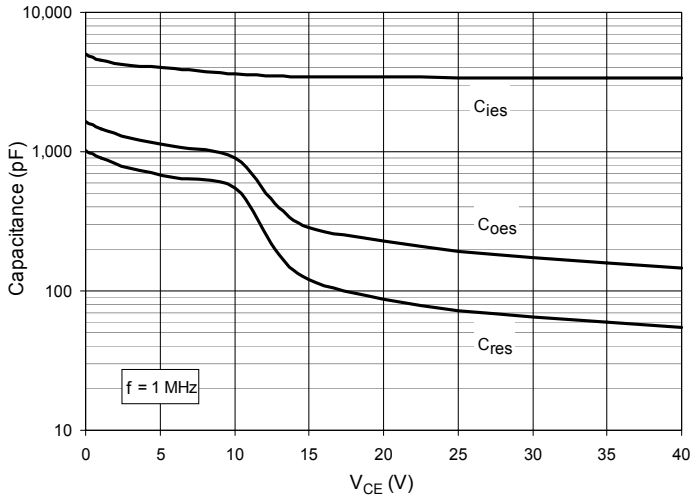
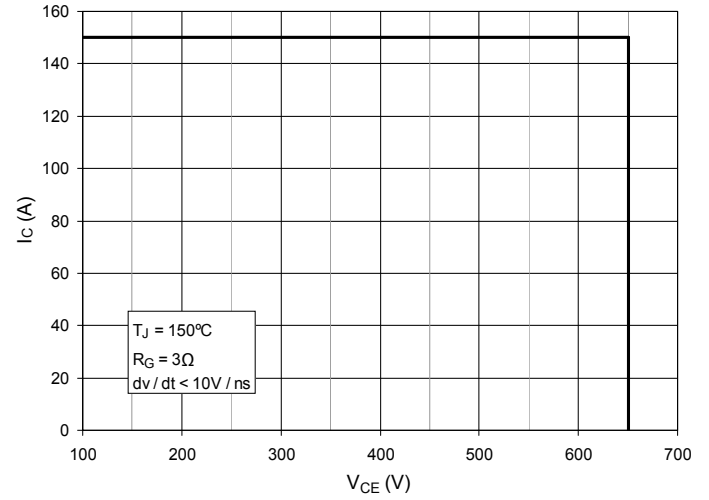
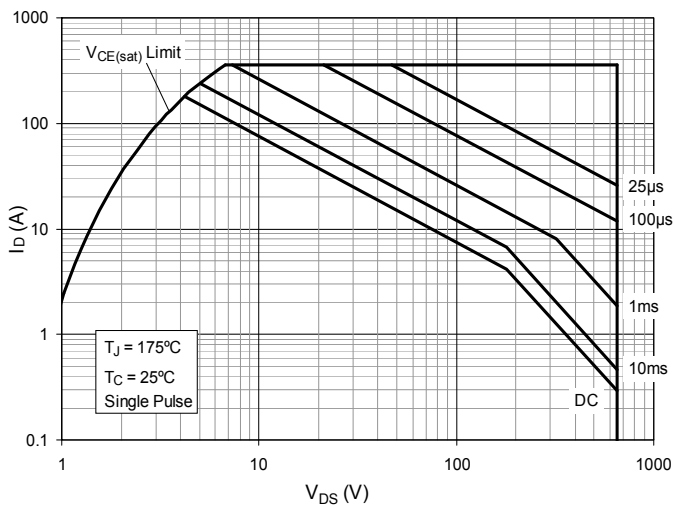
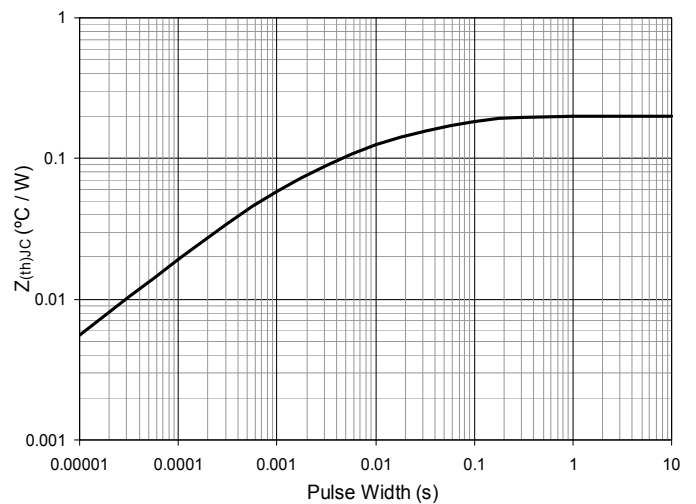
Fig. 7. Transconductance

Fig. 8. Gate Charge

Fig. 9. Capacitance

Fig. 10. Reverse-Bias Safe Operating Area

Fig. 11. Forward-Bias Safe Operating Area

Fig. 12. Maximum Transient Thermal Impedance (IGBT)


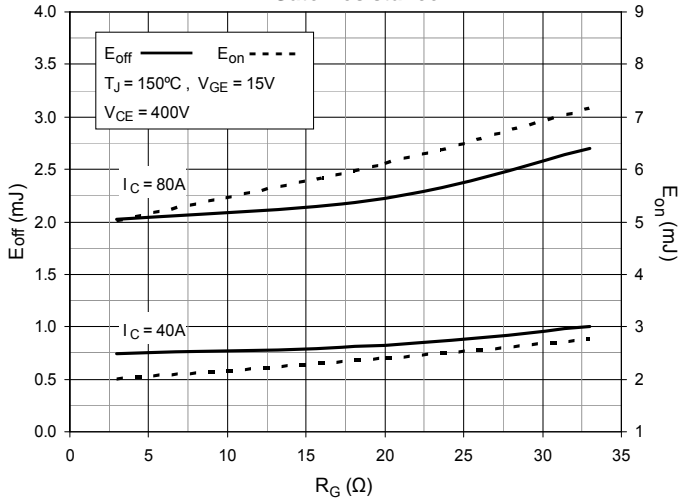
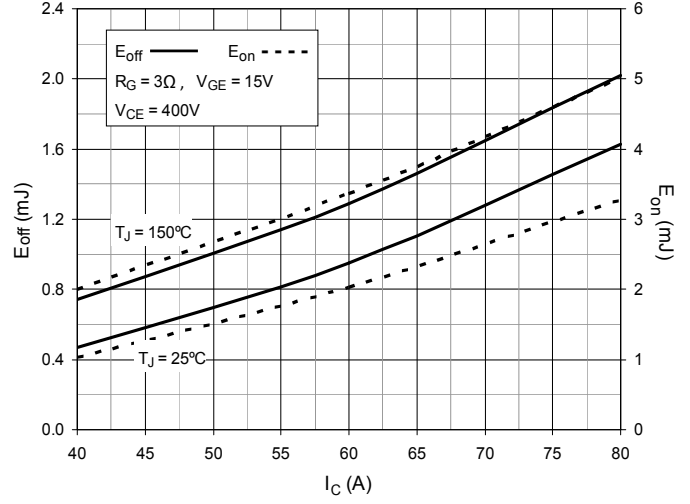
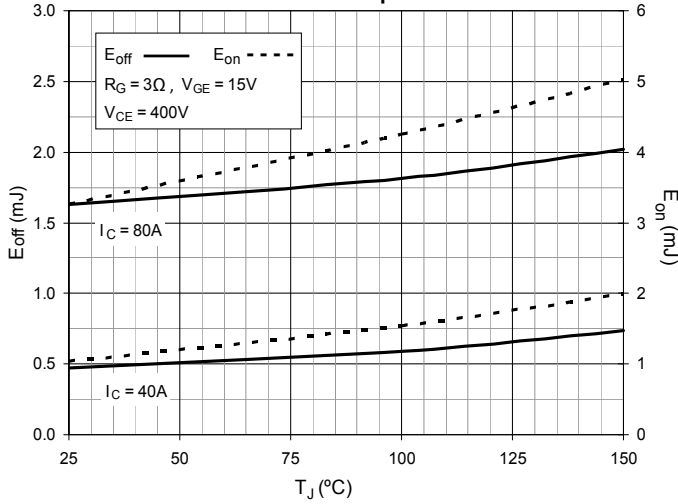
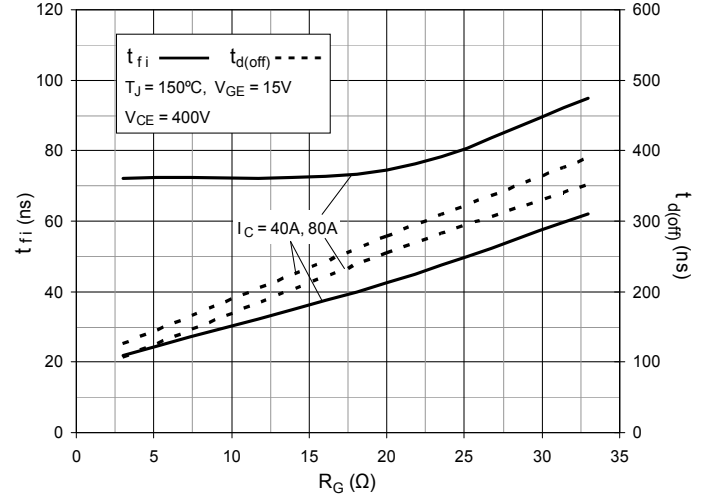
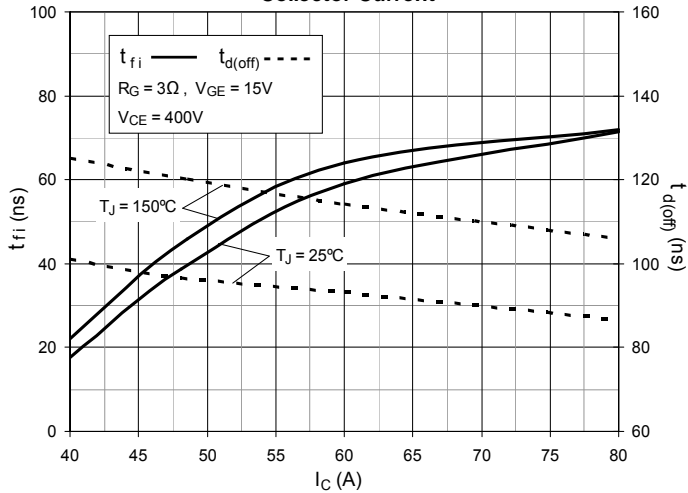
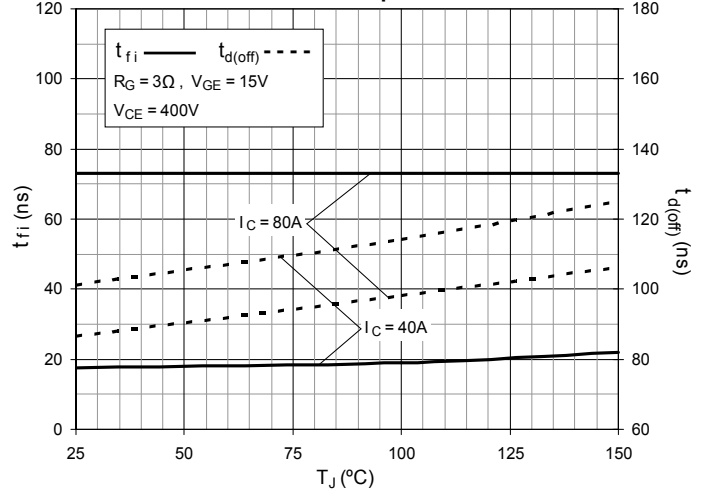
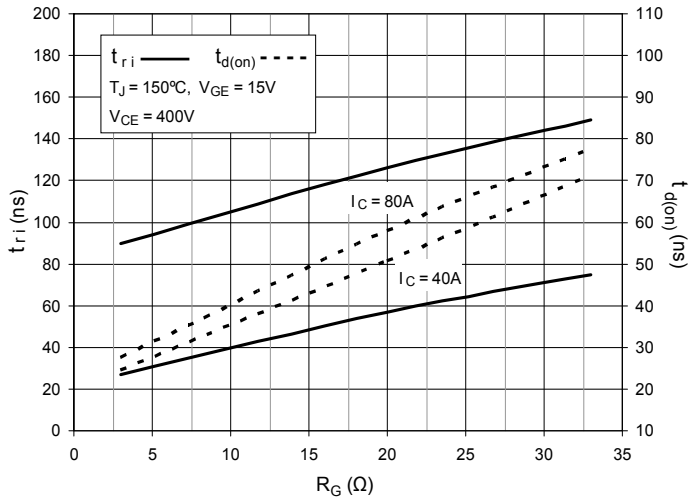
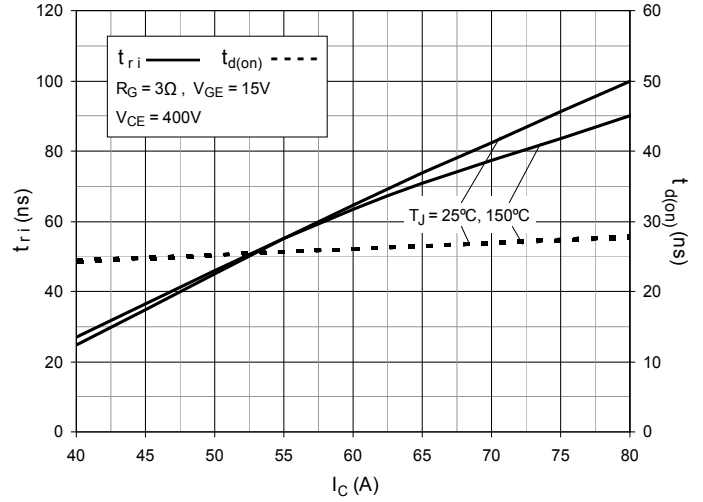
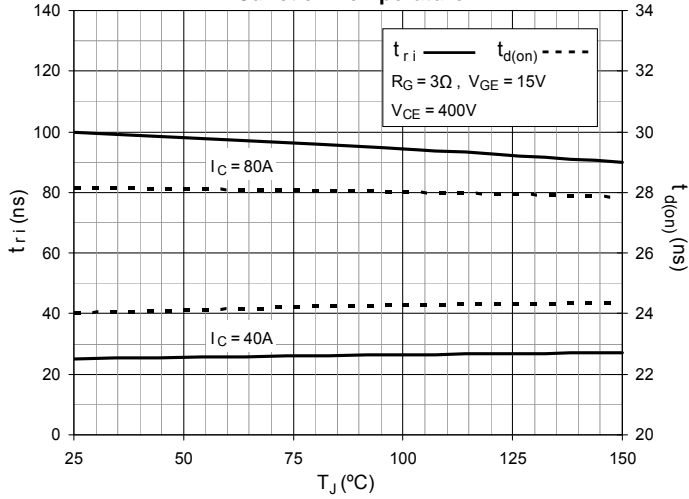
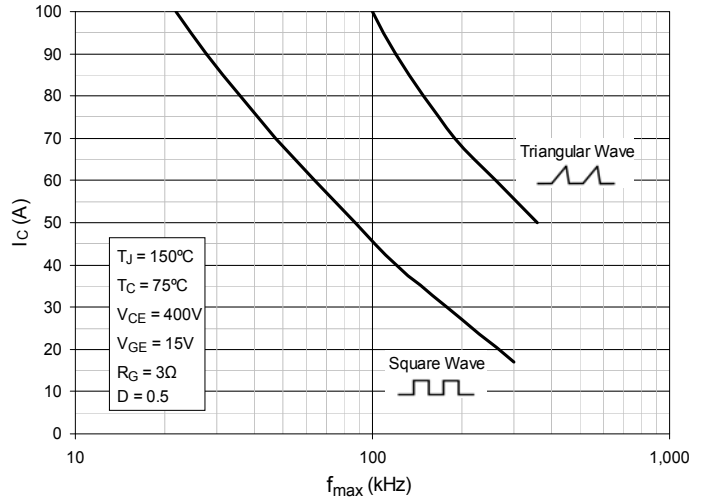
Fig. 13. Inductive Switching Energy Loss vs. Gate Resistance

Fig. 14. Inductive Switching Energy Loss vs. Collector Current

Fig. 15. Inductive Switching Energy Loss vs. Junction Temperature

Fig. 16. Inductive Turn-off Switching Times vs. Gate Resistance

Fig. 17. Inductive Turn-off Switching Times vs. Collector Current

Fig. 18. Inductive Turn-off Switching Times vs. Junction Temperature


Fig. 19. Inductive Turn-on Switching Times vs. Gate Resistance

Fig. 20. Inductive Turn-on Switching Times vs. Collector Current

Fig. 21. Inductive Turn-on Switching Times vs. Junction Temperature

Fig. 22. Maximum Peak Load Current vs. Frequency




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